IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

LARRY ZHAO JEREMY MARTIN HARTMUT RUELKE

Serial No.: 10/717,122

Filed: November 19, 2003

For: DIELECTRIC BARRIER LAYER FOR A
COPPER METALLIZATION LAYER
HAVING A VARYING SILICON
CONCENTRATION ALONG ITS

THICKNESS

Confirmation No.: 7303

Examiner: Alexander G. Ghyka

Group Art Unit: 2812

Att'y Docket: 2000.106900/DE0130

Customer No.: 23720

RESPONSE TO OFFICE ACTION DATED JANUARY 3, 2007

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

This paper is submitted in response to the Office Action dated January 3, 2007, for which the three-month date for response was April 3, 2007. A request for a three-month extension of time to respond is included herewith. This three-month extension will bring the due date to July 3, 2007, which is within the six-month statutory period.

A fee in the amount of \$1,020 is believed to be due in connection with the present paper. The Director is authorized to deduct such fee, and any other fees required under 37 C.F.R. \$\\$ 1.16 to 1.21, from Williams, Morgan & Amerson, P.C. Deposit Account No. 50-0786/5000.000300.

Reconsideration of the application in view of the following amendments and remarks is respectfully requested.